Data sheet

Accessory

Low Melt glue sticks Ø 11 mm

EAN 4007841052409

Functional description

Its low melting temperature makes the Low-Melt adhesive particularly suitable for heat-sensitive materials, such as PU foam and polystyrene. With an application temperature of only 130°C, it protects the base surface it is applied to. The material is firm after a maximum of 80 seconds, with a strong bond being provided after approx. 40 seconds. (Times and recommended adhesive are rough guides only).

Technical specifications

Melt temperature	130 °C
Suitable for	Paper, Card / cardboard boxes, Rubber, Rubber (CR), ABS, POM, Rigid PVC, PU foam, Polystyrene
Glue reaches final strength after:	12 h
Thermally stable	5 – 50 °C
Open time	40 s
Setting time	80 s
Solvent-free	Yes
Version	20 ea. (600 g)
PU1, net weight	0,600 kg